Final Product Change Notification

201806004F01

Issue Date: 22-Jun-2018
Effective Date: 20-Sep-2018

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[X] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[ ] Other			

New Die Attach Qualification for PDIP Package in TongFuMicroelectronics Co. LTD

Description of Change

NXP Semiconductors announces the qualification of epoxy CRM-1033BF for PDIP package in TongFu Microelectronics Co. LTD, Nantong, China (TFME) Facility.

Reason for Change

The new die attach qualification for PDIP is required for supply assurance.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available from 04-Jul-2018

The following sample part numbers are available:

PC68HC908QT1MPE

PC908QY4ACPE
Production
Planned first shipment 25-Sep-2018

Anticipated Impact on Form, Fit, Function, Reliability or Quality

There is no change to product form, fit, function, or reliability

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 22-Jul-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
MC9S08QG8CPBE	935322628174	MC9S08QG8CPBE	CONSUMER ROO 9S08QG	SOT38-10	DIP16	RFS	BL Microcontrollers
MC68HC908QT2CPE	935309366174	MC68HC908QT2CPE	1.5K FLASH W/ADC	SOT97-3	DIP8	RFS	BL Microcontrollers
MC68HC908QT4CPE	935325162174	MC68HC908QT4CPE	4K FLASH W/ADC	SOT97-3	DIP8	RFS	BL Microcontrollers